



Click [here](#) for the 3D model.

Dimensions

| | |
|-----------|--|
| Chip Size | 0402 |
| L | 1.02mm +0.15/-0.1mm (0.04 in +0.006/-0.004 in) |
| W | 0.51mm +0.13/-0.1mm (0.02 in +0.005/-0.004 in) |
| T | 0.64mm MAX (0.025 in MAX) |
| B | 0.1mm MIN (0.004 in MIN) |

Packaging Specifications

| | |
|--------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 368 |

General Information

| | |
|----------------|-----------------------------|
| Series | SMD MIL COG PRF32535 |
| Style | SMD Chip |
| Description | SMD, Low ESR, MIL-PRF-32535 |
| RoHS | Yes |
| Termination | Gold |
| Failure Rate | N/A |
| Qualifications | MIL-PRF-32535 M-Level |
| AEC-Q200 | No |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|---------------------------------|---------------------|
| Capacitance | 100 pF |
| Capacitance Tolerance | 5% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | COG |
| Dissipation Factor | 0.15% 1 MHz 25C |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)